

注記 NOTES

1. 使用材料 MATERIAL

ウェハ：液晶ポリマー (LCP) ガラス充填 UL94V-0 (黒)
 WAFER : LIQUID CRYSTAL POLYMER (GLASS FILLED)
 UL94V-0 (COLOR:BLACK)

ピン：黄銅 (t=0.1)
 PIN : BRASS (t=0.1)

金具：りん青銅 (t=0.12)
 FITTING NAIL : PHOSPHOR BRONZE (t=0.12)

2. メッキ仕様 PLATING

ピン PIN

金メッキ 0.2 マイクロメートル以上 (コンタクト部)
 GOLD 0.2MICROMETER MINIMUM (CONTACT AREA)

金メッキ 0.4 マイクロメートル以下 (テール部)
 GOLD 0.4 MICROMETER MAXIMUM (TAIL AREA)

下地メッキ：ニッケルメッキ 1.5 マイクロメートル以上
 UNDER PLATING : NICKEL 1.5MICROMETER MINIMUM

金具 FITTING NAIL

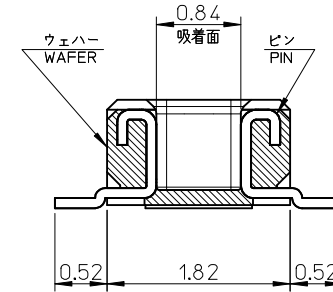
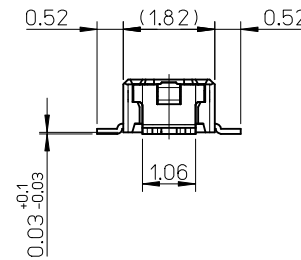
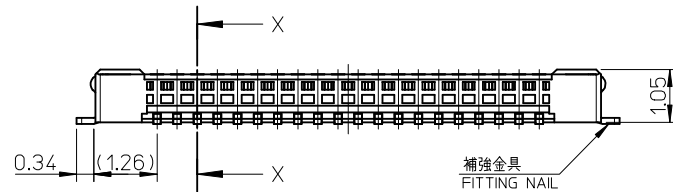
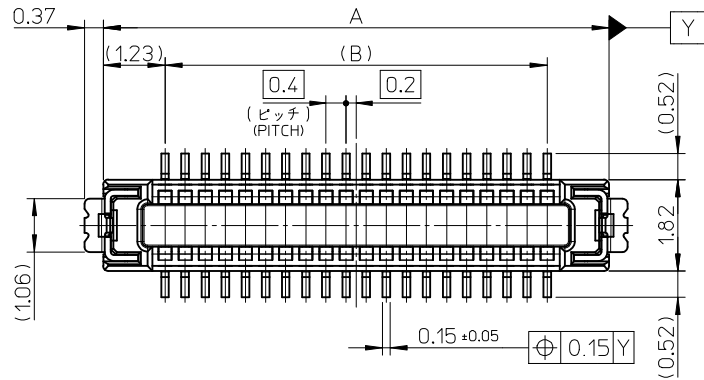
半田付け処理 (金・パラジウムコート)
 SOLDERABILITY IMPROVEMENT COAT (Au & Pd-Ni COAT)

下地メッキ：ニッケルメッキ 1.0 マイクロメートル以上
 UNDER PLATING : NICKEL 1.0MICROMETER MINIMUM

△ (全極数/2) = 偶数の場合に適用。
 APPLY OFR (CIRCUIT/2)=EVEN.

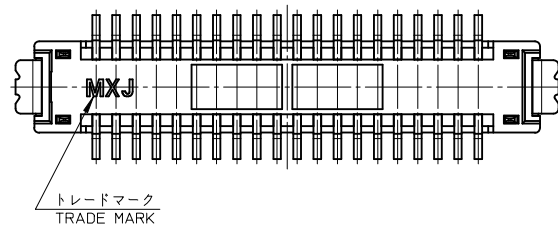
4. 嵌合相手：501527 シリーズ
 MATE WITH : 501527 SERIES.

5. テール平坦度は、0.08 以下
 テール及び金具の平坦度は、0.1 以下
 TAIL COPLANARITY TO BE 0.08MAXIMUM
 TAIL AND FITTING NAIL
 COPLANARITY TO BE 0.1MAXIMUM



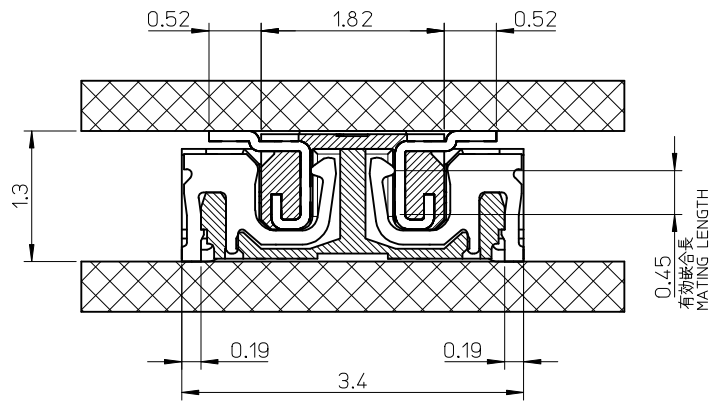
SECTION X-X

9.6	12.06	501531-0510	501531-0519	50
7.6	10.06	501531-0410	501531-0419	40
6.4	8.86	501531-3410	501531-3419	34
6.0	8.46	501531-3210	501531-3219	32
5.6	8.06	501531-0310	501531-0319	30
3.6	6.06	501531-0210	501531-0219	20
B	A	EMBOSSED TAPE PKG.	MATERIAL No.	CKT
		ORDER No. オーダー番号	MODEL No. : 501531-**-19	

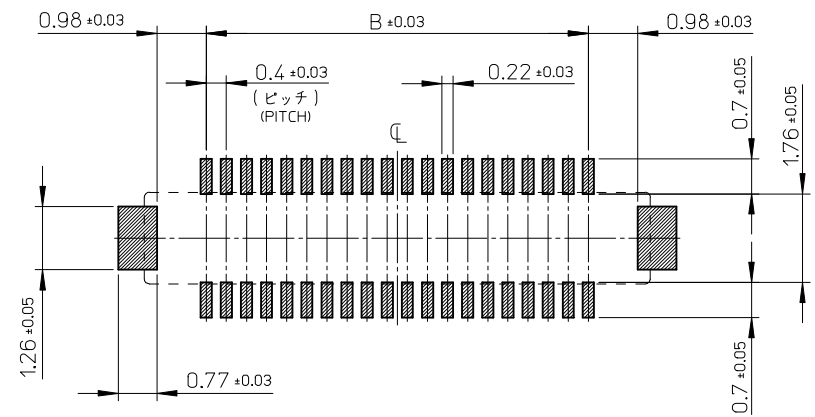


REVISED EC NO: J2017-0224 DRM/NISHIKAWA 2016/10/12 CHKD: TAKAHASHI 2016/10/12 APPR: MSASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±	DRAWN BY RTAKEUCHI	DATE 2005/10/25	TITLE 0.4 B-TO-B CONN. HGT=1.3 PLUG ASSY [OVERMOLD] -LEAD FREE-		
	0.25 OVER 0.5 UNDER	±	CHECKED BY THIRATA	DATE 2005/10/25			
	0.5 OVER 1.0 UNDER	±	APPROVED BY MSASAO	DATE 2005/10/25			
10 OVER 30 UNDER	±0.25	MATERIAL NO.		SEE CHART	DOCUMENT NO. SD-501531-001	SHEET NO. 1 OF 2	
30 OVER	±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



嵌合断面図 (参考)
MATED DRAWING (REFERENCE)



参考基板レイアウト (マウント面)
P.C.BOARD PATTERN DIMENSION (REFERENCE)
(MOUNTING AREA)

REVISED EC NO: J2017-0224 DRWN: NISHIKAWA 2016/10/12 CHKD: TAKAHASHI 2016/10/12 APPR: MSASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
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	0.5 OVER 1.0 UNDER	±	APPROVED BY MSASAO	DATE 2005/10/25			
	0 OVER 10 UNDER	±0.2	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	2 OF 2	
10 OVER 30 UNDER	±0.25	SEE SHEET 1		SD-501531-001			
30 OVER	±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
ANGULAR	±3 °	SIZE A3					

9 8 7 6 5 4 3 2 1

注記 NOTES

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2. メッキ仕様 PLATING

ピン PIN

金メッキ 0.2 マイクロメートル以上 (コンタクト部)
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下地メッキ：ニッケルメッキ 1.5 マイクロメートル以上
 UNDER PLATING : NICKEL 1.5MICROMETER MINIMUM

金具 FITTING NAIL

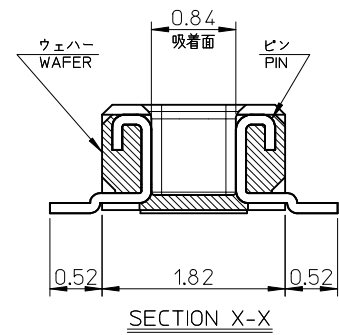
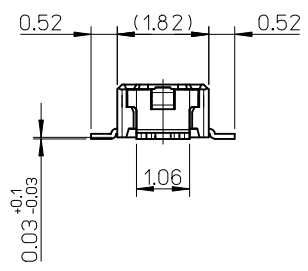
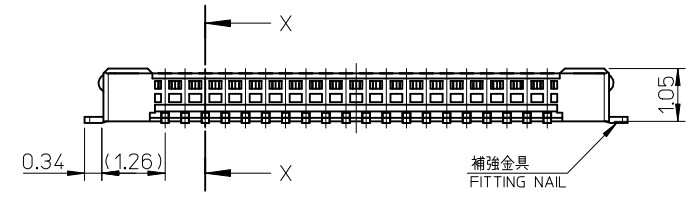
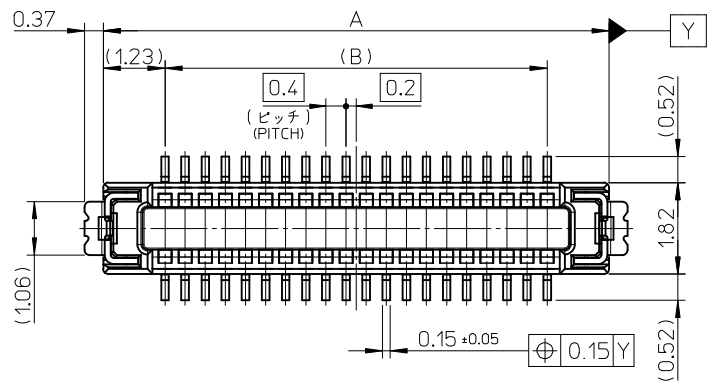
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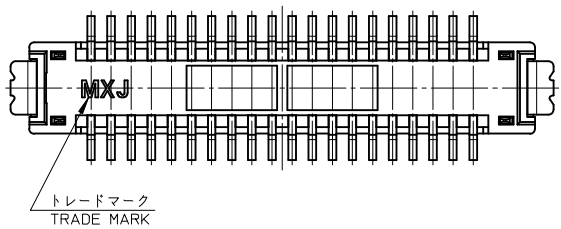
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 APPLY OFR (CIRCUIT/2)=EVEN.

4. 嵌合相手：501527 シリーズ
 MATE WITH : 501527 SERIES.

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 テール及び金具の平坦度は、0.1 以下
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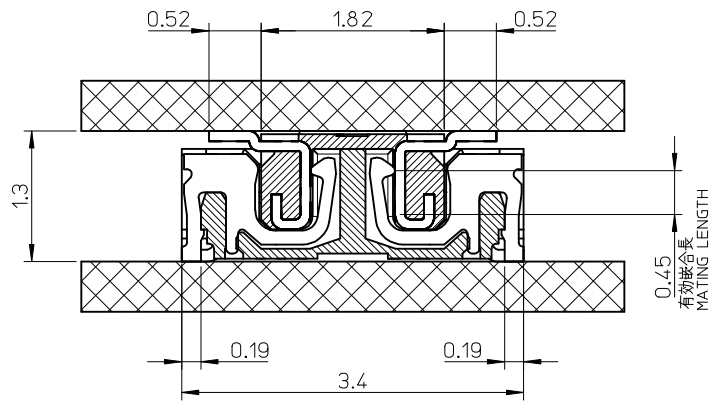


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B	A	EMBOSSED TAPE PKG.	MATERIAL No.	CKT
		ORDER No. オーダー番号	MODEL No. : 501531-**-19	

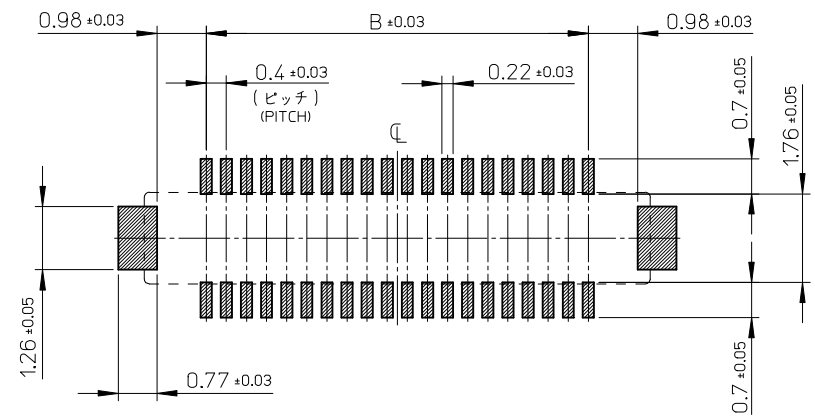


REVISED EC NO: J2017-0224 DRM/NISHIKAWA 2016/10/12 CHKD: TAKAHASHI 2016/10/12 APPR: MSASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER ±	DRAWN BY RTAKEUCHI	DATE 2005/10/25	TITLE 0.4 B-TO-B CONN. HGT=1.3 PLUG ASSY [OVERMOLD] -LEAD FREE-	
	0.25 OVER 0.5 UNDER ±	CHECKED BY THIRATA	DATE 2005/10/25		
	0.5 OVER 1.0 UNDER ±	APPROVED BY MSASAO	DATE 2005/10/25		
10 OVER 30 UNDER ±0.25	MATERIAL NO.	SEE CHART	DOCUMENT NO. SD-501531-001	SHEET NO. 1 OF 2	
30 OVER ±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
ANGULAR ±3 °					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
SIZE A3					

10 9 8 7 6 5 4 3 2 1



嵌合断面図 (参考)
MATED DRAWING (REFERENCE)



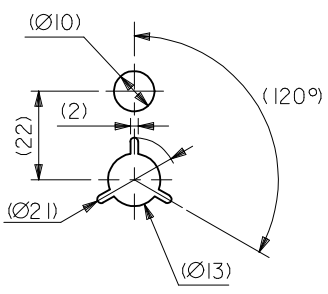
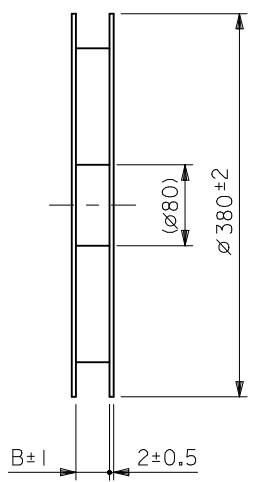
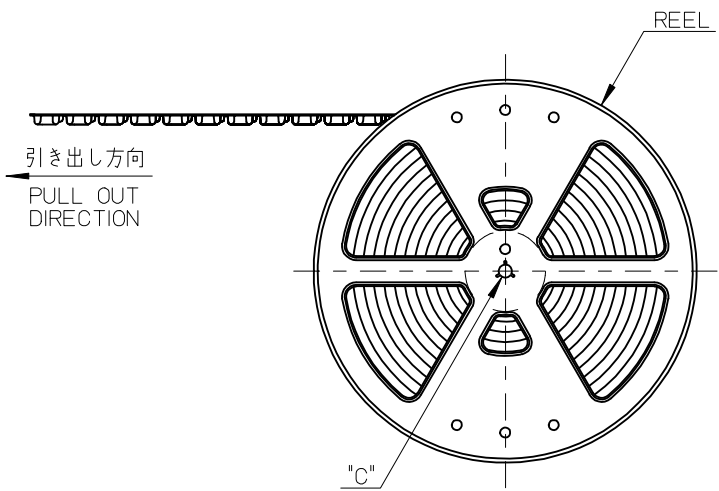
参考基板レイアウト (マウント面)
P.C.BOARD PATTERN DIMENSION (REFERENCE)
(MOUNTING AREA)

REVISED EC NO: J2017-0224 DRWN: NISHIKAWA 2016/10/12 CHKD: TAKAHASHI 2016/10/12 APPR: MSASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	0.25 UNDER	±	DRAWN BY RTAKEUCHI	DATE 2005/10/25	TITLE 0.4 B-TO-B CONN. HGT=1.3 PLUG ASSY [OVERMOLD] -LEAD FREE-				
	0.25 OVER 0.5 UNDER	±	CHECKED BY THIRATA	DATE 2005/10/25	<div style="text-align: center; font-weight: bold; font-size: 1.2em;">molex</div>				
	0.5 OVER 1.0 UNDER	±	APPROVED BY MSASAO	DATE 2005/10/25					
	0 OVER 10 UNDER	±0.2	MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-501531-001	SHEET NO. 2 OF 2			
10 OVER 30 UNDER	±0.25	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
30 OVER	±0.3								
ANGULAR	±3 °								
REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								

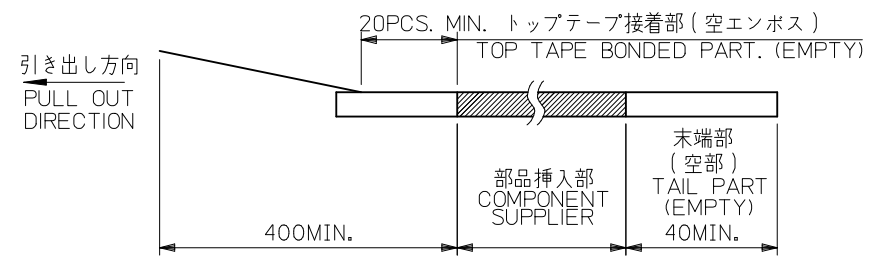
9 8 7 6 5 4 3 2 1

注記 NOTES

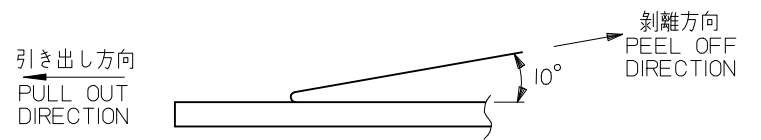
1. 製品詳細寸法については製品単体図面を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
2. 梱包数量：6000 個/リール
NUMBER OF CONNECTORS : 6000PCS/REEL
3. リードテープ長さ LEAD TAPE LENGTH



DETAIL "C"

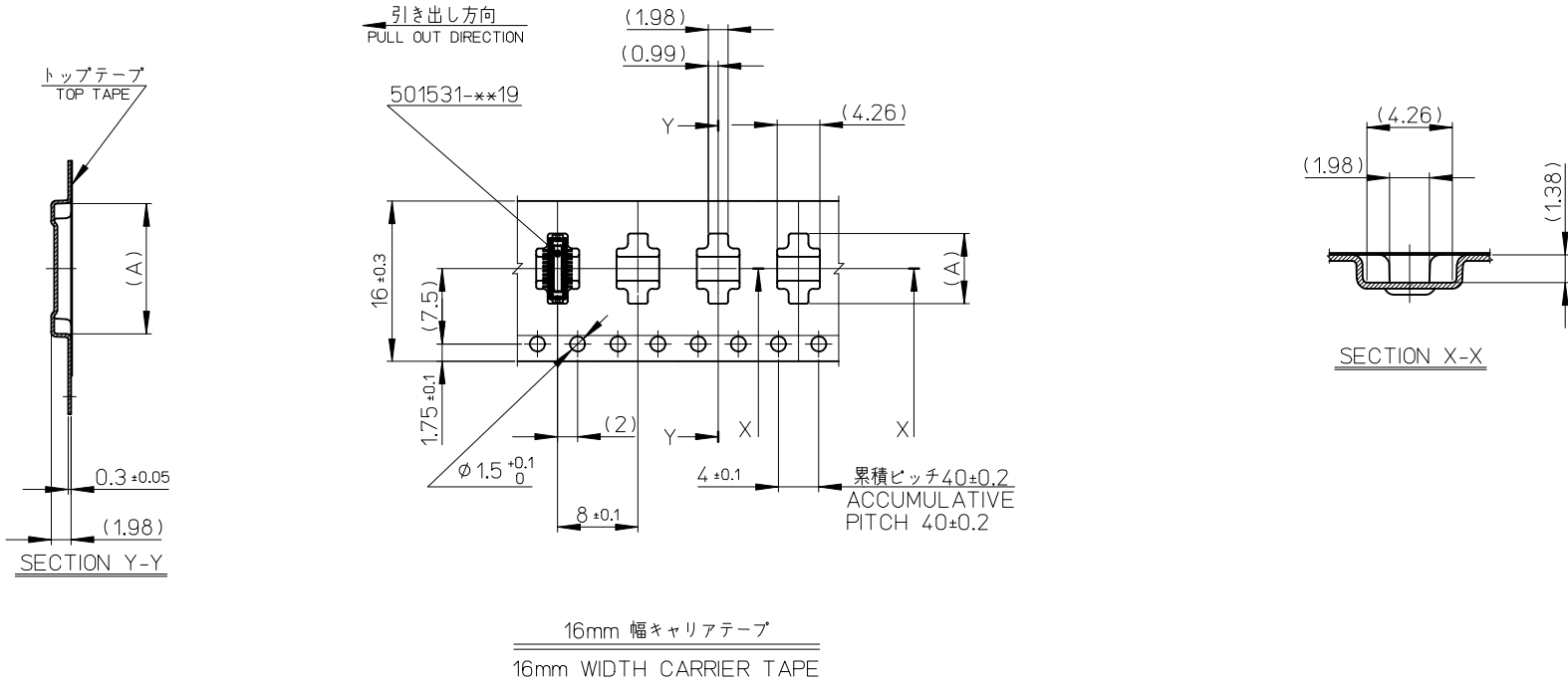


4. トップテープの剥離強度：JES-59 参照
剥離方向は下図参照。
PEELING OFF STRENGTH OF TOP TAPE : REFER TO JES-59
PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE.



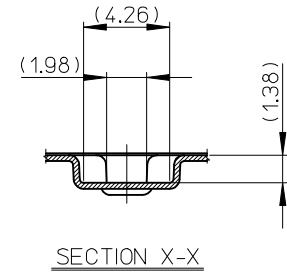
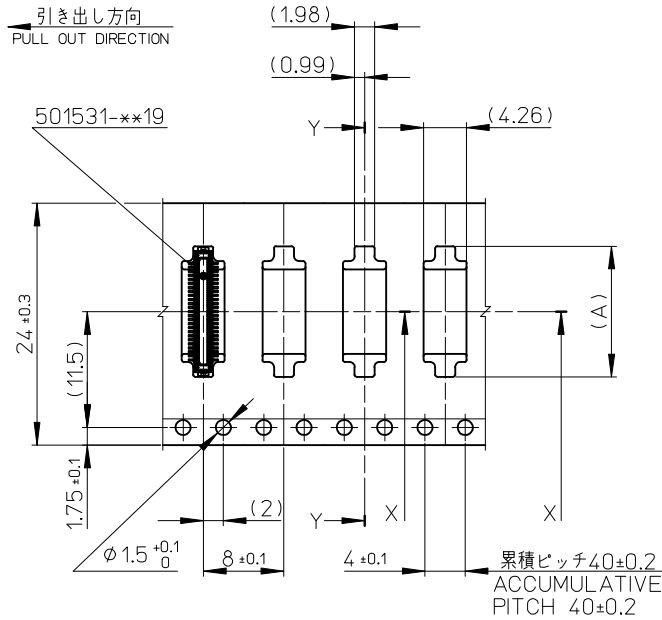
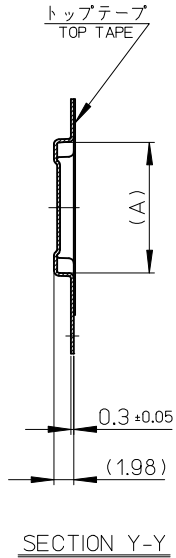
5. 材料 MATERIAL
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

REVISED EC NO: J2016-1237 DRWN: MISHIKAWA 2016/06/09 CHKD: Y0110 2016/06/09 APPR: Y0110 2016/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	MODEL NO.	501531-**10
	0.25 UNDER UNDER ±0.03		MM ONLY		---	METRIC	THIRD ANGLE PROJECTION	
	0.25 OVER 0.5 UNDER ±0.05		DRAWN BY DATE		TITLE			
	0.5 OVER 1.0 UNDER ±0.1		RTAKEUCHI 2005/10/27		0.4 B-TO-B CONN. HGT=1.3 PLUG ASSY EMBSTP PKG -LEAD FREE-			
	1.0 OVER 10 UNDER ±---		CHECKED BY DATE					
	10 OVER 30 UNDER ±---		THIRATA 2005/10/27					
30 OVER ±---		APPROVED BY DATE		MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
ANGULAR ±--- °		MSASAO 2005/10/27		SEE CHART		SD-501531-002	1 OF 3	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		A3						



16	17.5	6.96	501531-0210	20
キャリアテープ幅 CARRIER TAPE WIDTH		B	(A)	MATERIAL No. 501531-0210 CKT. 501531-**10

REVISED EC NO: J2016-1237 DRWN: MISHIKAWA 2016/06/09 CHKD: Y0110 2016/06/09 APPR: Y0110 2016/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	RTAKEUCHI	2005/10/27	0.4 B-TO-B CONN. HGT=1.3 PLUG ASSY EMBSTP PKG -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±0.1	THIRATA	2005/10/27			
	1.0 OVER	10 UNDER	±---	APPROVED BY	DATE	molex DOCUMENT NO. SD-501531-002 SHEET NO. 2 OF 3		
10 OVER	30 UNDER	±---	MSASAO	2005/10/27				
30 OVER		±---	MATERIAL NO.		SEE CHART			
ANGULAR	±--- °		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								



24mm 幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	25.5	12.96	501531-0510	50	
		10.96	501531-0410	40	
		9.76	501531-3410	34	
		9.36	501531-3210	32	
		8.96	501531-0310	30	
キャリアテープ幅 CARRIER TAPE WIDTH		B	(A)	MATERIAL No.	CKT.
			MODEL No.	501531-**-10	

REVISED EC NO: J2016-1237 DRWN: MISHIKAWA CHKD: Y0110 APPR: Y0110	DESCRIPTION 2016/06/09 2016/06/09 2016/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS		TITLE 0.4 B-TO-B CONN. HGT=1.3 PLUG ASSY EMBSTP PKG -LEAD FREE- molex DOCUMENT NO. SD-501531-002 SHEET NO. 3 OF 3	
		0.25 UNDER UNDER ±0.03			MM ONLY		---	METRIC			THIRD ANGLE PROJECTION
		0.25 OVER 0.5 UNDER ±0.05			DRAWN BY DATE		RTAKEUCHI 2005/10/27				
		0.5 OVER 1.0 UNDER ±0.1			CHECKED BY DATE		THIRATA 2005/10/27				
		1.0 OVER 10 UNDER ±---			APPROVED BY DATE		MSASAO 2005/10/27				
30 OVER ±---			MATERIAL NO.		SEE CHART						
ANGULAR ±---°			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				